IN THE CLAIMS:

Please amend claims 1, 2 and 7 as shown below, in which deleted terms are indicated with strikethrough and/or double brackets, and added terms are indicated with underscoring. The following list of claims replaces all previous versions, and listings of claims in the application.

1. (Currently Amended) An apparatus for testing infrared cameras, comprising:

a cover plate which has a plurality of holes formed therethrough and arranged in line, said cover plate adapted to emit an amount of infrared light;

a pair of spaced-apart support pillars formed from a material having low thermal conductivity, the cover plate being operatively attached to the support pillars so as to be vertically adjustable thereon; and

an emission source which is operatively attached to the support pillars and disposed in parallel to and behind the cover plate as viewed from infrared cameras to be tested, and which is adapted to emit a different amount of infrared light when compared with the cover plate, the emission source comprising a metal plate, and an element which is adhered to the metal plate, and which has an infrared emissivity that is different from that of the cover plate.

2. (Currently Amended) An apparatus for testing infrared cameras, according to claim 1, wherein the emission source comprises ~~a metal plate, and~~ a heat source which is connected to the metal plate.

3. (Previously Presented) An apparatus for testing infrared cameras, comprising:

a cover plate which has holes arranged in line, and which is adapted to emit an amount of

infrared light; and

an emission source which is disposed in parallel to and behind the cover plate as viewed from infrared cameras to be tested, and which is adapted to emit a different amount of infrared light when compared with the cover plate,

wherein the emission source comprises a metal plate, and an element which is adhered to the metal plate, and which has an infrared emissivity that is higher than that of the cover plate.

4. (Original) An apparatus for testing infrared cameras, according to claim 1, wherein the cover plate has been subjected to a processing for reducing infrared reflection.

5. (Previously Presented) An apparatus for testing infrared cameras, comprising: a cover plate which has holes arranged in line, and which is adapted to emit an amount of infrared light; and an emission source which is disposed in parallel to and behind the cover plate as viewed from infrared cameras to be tested, and which is adapted to emit a different amount of infrared light when compared with the cover plate;

wherein the cover plate is vertically movable in front of the emission source as viewed from the infrared cameras to be tested from a first position at which testing of the infrared cameras is executed to a second position which is higher than the first position.

6. (Original) An apparatus for testing infrared cameras, according to claim 5, wherein the second position is sufficiently higher than the first position such that the cover plate is not heated by a heat source of the emission source.

7. (Currently Amended) An apparatus for testing infrared cameras according to claim 1, wherein the emission source comprises ~~a metal plate, and~~ a heating and cooling source which is connected to the metal plate.

8. (Previously Presented) An apparatus for testing infrared cameras according to claim 3, wherein said metal plate is aluminum.

9. (Original) An apparatus for testing infrared cameras according to claim 1, wherein paper is adhered to a front of said cover plate to reduce infrared reflection therefrom.

10. (Previously Presented) An apparatus for testing infrared cameras according to claim 3, further including pillars along which at least one of the metal plate and cover plate are vertically movable.

11. (Previously Presented) An apparatus for testing infrared cameras according to claim 10, wherein both said metal plate and cover plate are vertically movable along said pillars.

12. (Previously Presented) An apparatus for testing infrared cameras according to claim 10, wherein said pillars are formed of a material having low thermal conductivity.